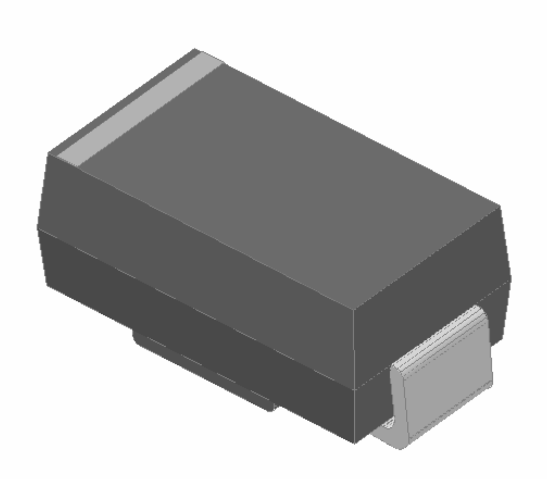
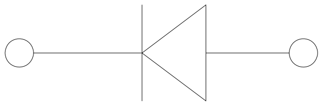


- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.



- : DO-214AC (SMA) Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- : Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Cathode line denotes the cathode end

■ (Ta=25 Unless otherwise specified

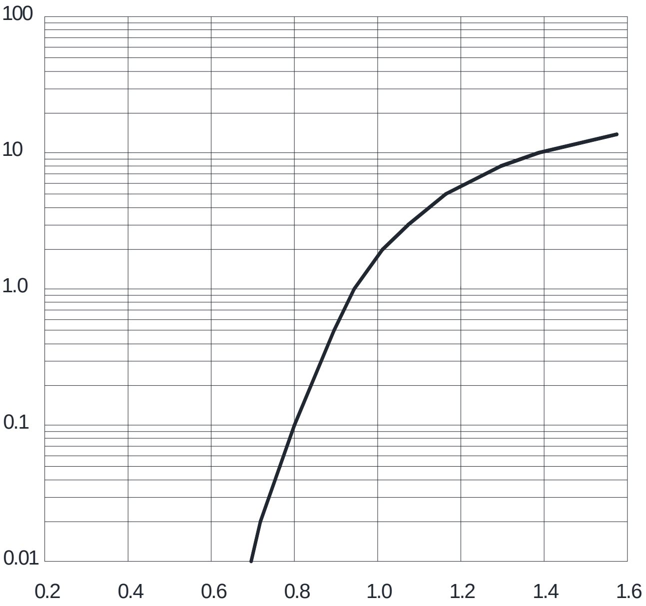
~~Device markip ₇אנ א l o Ě M א~~	~~א я~~		

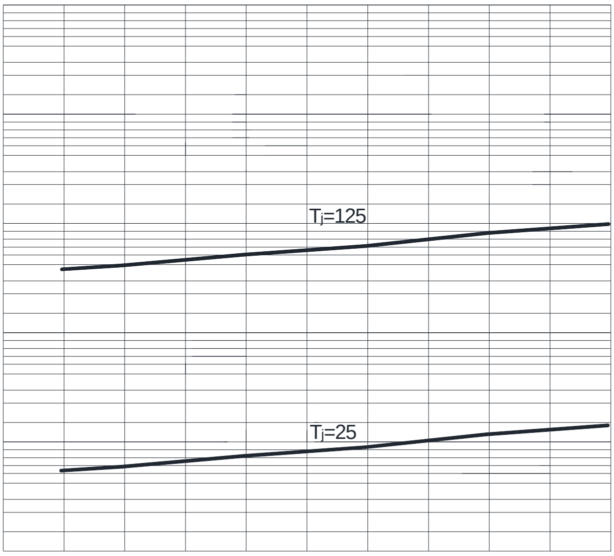
Forward Surge Current (Non-repetitive) ~~@60Hz Half-sine wave,1 cycle, Tj=25~~	I_{FSM}	A	30
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25			60
~~Current squared time~~ @1ms≤t≤8.3ms Tj=25	I^2t	A^2s	3.735
Storage temperature	Tstg		-55 ~ +150
Junction temperature	Tj		-55 ~ +150

■ Ta=25 Unless otherwise specified

Maximum instantaneous forward voltage	VF	V	IFM=1.0A	1.1
Maximum DC reverse current at rated DC blocking voltage	IR	µA	Tj =25	5
			Tj =125	100
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	8

■ T_a=25 Unless otherwise specified





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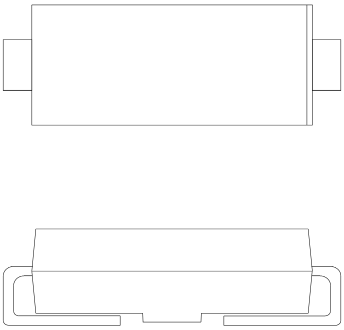
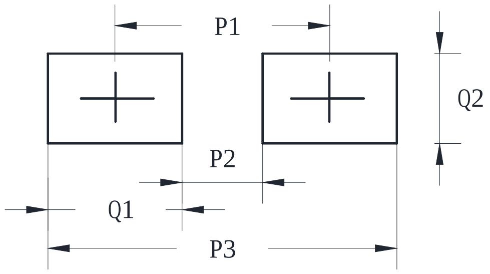
DO-214AC(SMA)



Dimensions in millimeters

Dim	Min	Max
A	1.25	1.58
B	2.40	2.83
C	4.00	4.75
D	1.90	2.30
E	4.93	5.28
F	0.76	1.41
G	0.05	0.20
H	0.15	0.31
I	1.70	2.10



Dimensions in millimeters

Dim	Millimeters
P1	4.00
P2	1.50
P3	6.50
Q1	2.50
Q2	1.70